RELIABILITY REPORT

FOR

DG407DN+

PLASTIC ENCAPSULATED DEVICES

August 24, 2010

MAXIM INTEGRATED PRODUCTS

120 SAN GABRIEL DR.

SUNNYVALE, CA 94086

Approved by
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Conclusion

The DG407DN+ successfully meets the quality and reliability standards required of all Maxim products. In addition, Maxim"s continuous reliability monitoring program ensures that all outgoing product will continue to meet Maxim"s quality and reliability standards.

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I. Device Description

A. General

Maxim's redesigned DG406 and DG407 CMOS analog multiplexers now feature guaranteed matching between channels (8 max) and flatness over the specified signal range (9 max). These low on-resistance muxes (100 max) conduct equally well in either direction and feature guaranteed low charge injection (15pC max). In addition, these new muxes offer low input off-leakage current over temperatureµless than 5nA at +85°C. The DG406 is a 1 of 16 multiplexer/demultiplexer and the DG407 is a dual 8-channel multiplexer/demultiplexer. Both muxes operate with a +5V to +30V single supply and with ±4.5V to ±20V dual supplies. ESD protection is guaranteed to be greater than 2000V per Method 3015.7 of MIL-STD 883. These improved muxes are pin-compatible plug-in upgrades for the industry standard DG406 and DG407.

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II. Manufacturing Information

A. Description/Function:	Improved, 16-Channel/Dual 8-Channel, CMOS Analog Multiplexers
B. Process:	S5
C. Number of Device Transistors:	
D. Fabrication Location:	Oregon
E. Assembly Location:	Philippines
F. Date of Initial Production:	Pre 1997

III. Packaging Information

A. Package Type:	28-pin PLCC
B. Lead Frame:	Copper
C. Lead Finish:	100% matte Tin
D. Die Attach:	Conductive
E. Bondwire:	Au (1.3 mil dia.)
F. Mold Material:	Epoxy with silica filler
G. Assembly Diagram:	#05-0301-0647
H. Flammability Rating:	Class UL94-V0
I. Classification of Moisture Sensitivity per JEDEC standard J-STD-020-C	Level 1
J. Single Layer Theta Ja:	95°C/W
K. Single Layer Theta Jc:	25°C/W
L. Multi Layer Theta Ja:	n/a
M. Multi Layer Theta Jc:	n/a

IV. Die Information

A. Dimensions:	98 X 184 mils
B. Passivation:	Si_3N_4/SiO_2 (Silicon nitride/ Silicon dioxide)
C. Interconnect:	Al/0.5%Cu with Ti/TiN Barrier
D. Backside Metallization:	None
E. Minimum Metal Width:	5.0 microns (as drawn)
F. Minimum Metal Spacing:	5.0 microns (as drawn)
G. Bondpad Dimensions:	5 mil. Sq.
H. Isolation Dielectric:	SiO_2
I. Die Separation Method:	Wafer Saw

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V. Quality Assurance Information

A. Quality Assurance Contacts: Don Lipps (Manager, Reliability Engineering)
Bryan Preeshl (Managing Director of QA)

B. Outgoing Inspection Level: 0.1% for all electrical parameters guaranteed by the Datasheet.
0.1% For all Visual Defects.

C. Observed Outgoing Defect Rate: < 50 ppm

D. Sampling Plan: Mil-Std-105D

VI. Reliability Evaluation

A. Accelerated Life Test

The results of the 135°C biased (static) life test are shown in Table 1. Using these results, the Failure Rate (λ) is calculated as follows:

$$\lambda = \frac{1}{MTTF} = \frac{1.83}{192 \times 4340 \times 80 \times 2}$$ (Chi square value for MTTF upper limit)

(where 4340 = Temperature Acceleration factor assuming an activation energy of 0.8eV)

$\lambda = 13.7 \times 10^{-9}$

λ = 13.7 F.I.T. (60% confidence level @ 25°C)

The following failure rate represents data collected from Maxim"s reliability monitor program. Maxim performs quarterly life test monitors on its processes. This data is published in the Reliability Report found at http://www.maxim-ic.com/qa/reliability/monitor. Cumulative monitor data for the S5 Process results in a FIT Rate of 0.09 @ 25C and 1.55 @ 55C (0.8 eV, 60% UCL)

B. Moisture Resistance Tests

The industry standard 85°C/85%RH or HAST testing is monitored per device process once a quarter.

C. E.S.D. and Latch-Up Testing (lot NSZBG4002C, D/C 9914)

The AG60-1 die type has been found to have all pins able to withstand a HBM transient pulse of +/-1000V per Mil-Std 883 Method 3015.7. Latch-Up testing has shown that this device withstands a current of +/-250mA.

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Table 1
Reliability Evaluation Test Results

DG407DN+

TEST ITEM	TEST CONDITION	FAILURE IDENTIFICATION	SAMPLE SIZE	NUMBER OF FAILURES	COMMENTS
Static Life Test (Note 1)					
	Ta = 135°C Biased Time = 192 hrs.	DC Parameters & functionality	80	0	NSZBG2011BQ, DC 9949

Note 1: Life Test Data may represent plastic DIP qualification lots.

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